

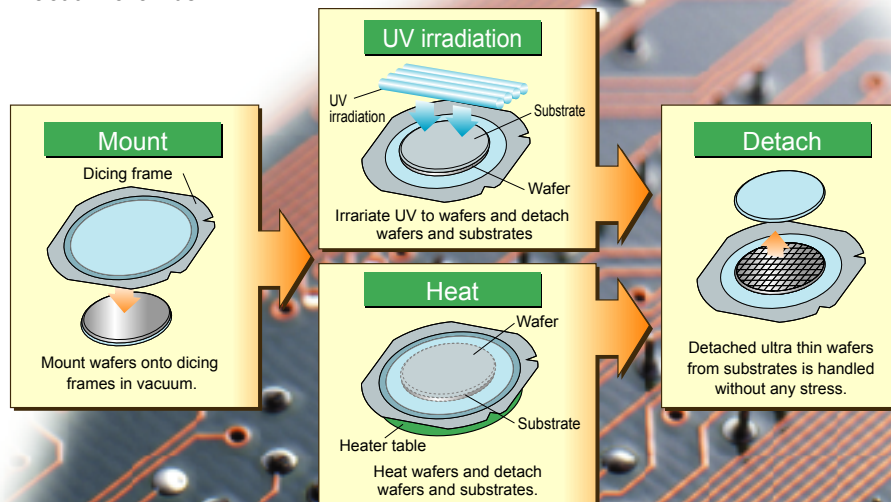
MODEL WSM-200

WAFER/SUBSTRATE DETACHING MACHINE
WITH MOUNTING FUNCTION

Outline

This machine mounts wafers which are attached with substrate in vacuum chamber, then irradiate UV (or heat) , then detach wafers and substrates.

No stress to wafers by Takatori unique thin wafer handling, vacuum element, vacuum chamber.



Specification	WSM-200
Throughput	40wafer/h
Wafer Size	6 inch, 8 inch
Dimensions	D1,800 × W1,800 × H1,800mm
Weight	1,100 (Incl. 200kg UV) kg

System appearance and specifications are subject to change without prior notice from the supplier.

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